

RZ/T1 Group

Data Operation Circuit (DOC)

APPLICATION NOTE

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Introduction

This application note describes a sample program that performs a failure detection test of the on-chip extended RAM (Data RAM 512KB) by using data comparison mode of the data operation circuit (DOC).

The major features of the program are listed below.

- The DOC compares data with reference data that is pre-set.
- When transfer of all data of the on-chip extended RAM (512 Kbytes) is complete, the DOC turns LED0 on. When the result of the comparison differs from the reference data, the DOC notifies an error to the error control module (ECM) and turns LED1 on by an ECM error detection interrupt.

Target Devices for Operation Checking

RZ/T1 Group

When applying the sample program covered in this application note to another microcomputer, modify the program according to the specifications for the target microcomputer and conduct an extensive evaluation of the modified program.



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1. Specifications

Table 1.1 lists the peripheral functions to be used and their applications and Figure 1.1 shows the operating environment.

Peripheral Function	Application
Clock pulse generator (CPG)	The CPG produces the CPU clock and low-speed on-chip oscilla- tor clock signals
Interrupt controller unit (ICUA)	The ICUA is used for ECM error detection maskable interrupt (ERRD), DMA transfer software startup interrupt (DMASRQ0), and DMA transfer error interrupt (DMAERR0).
Data operation circuit (DOC)	The DOC is used to compare data
DMA controller (DMACAa)	DMACAa transfers data in the on-chip extended RAM to the DOC data input register
Error control module (ECM)	The ECM is used to initialize the ERROROUT# pins and used for ECM error detection interrupts
General input/output port	The general I/O port is used to control pins for turning the LEDs on and off

 Table 1.1
 Peripheral Functions and Applications





2. Operating Environment

The sample program of this application is for the environment below.

Table 2.1 Operating Environment

Item	Description		
Microcomputer	RZ/T1 Group		
Operating frequency	CPUCLK = 450 MHz		
Operating voltage	3.3 V		
Integrated Development Environment	Manufactured by IAR Systems Embedded Workbench [®] for Arm Version 8.20.2 Manufactured by Arm DS-5 TM 5.26.2 Manufactured by RENESAS e2studio 6.1.0		
Operating modes	SPI boot mode 16-bit bus boot mode		
Board	RZ/T1 Evaluation board (RTK7910022C00000BR)		
Devices (functions to be used on the board)	 NOR flash memory (connected to CS0/CS1 space) Manufacturer: Macronix International Co. Ltd. Model: MX29GL512FLT2I-10Q SDRAM (connected to CS2/CS3 space) Manufacturer: Integrated Silicon Solution Inc. Model: IS42S16320D-7TL Serial flash memory Manufacturer: Macronix International Co. Ltd. Model: MX25L51245G 		



3. Related Documents

The application note related to this application note is given below for reference.

• RZ/T1 Group Initial Settings



4. Peripheral Functions

For the basics of the clock pulse generator (CPG), interrupt controller unit (ICUA), error control module (ECM), data operation circuit (DOC), DMA controller (DMAC), and general input/output port, refer to the RZ/T1 Group User's Manual: Hardware.



5. Hardware

5.1 Example of Hardware Configuration

Figure 5.1 shows an example of the hardware configuration.





5.2 Pins

 Table 5.1 lists pins to be used and their functions.

Table 5.1Pins and Functions

Pin Name	I/O	Function
MD0	Input	Selection of operating modes
MD1	Input	MD0 = L, MD1 = L, MD2 = L (SPI boot mode) MD0 = L, MD1 = H, MD2 = L (16-bit bus boot mode)
MD2	Input	
PF7	Output	Turning LED0 on and off
P56	Output	Turning LED1 on and off



6. Software

6.1 Operation Overview

The sample program makes the initial settings of the data operation circuit (DOC) by writing data to the on-chip extended RAM (AAH). Then, the data in the on-chip extended RAM is transferred to the DOC data input register in 16bit units in sequence by using the DMA controller (DMAC0). When the transfer of the all data in the on-chip extended RAM is complete, a DMA transfer complete interrupt is generated. LED0 is turned on in response to the interrupt processing.

When the value written in advance to the DOC data setting register and the data transferred to the DOC data input register do not match, the DOC notifies the ECM of an error and an ECM error detection interrupt is generated. LED1 is turned on as part of the interrupt processing.

Table 6.1 shows the operation overview of the sample program and Figure 6.1 illustrates the image of operations.

Function	Description	
Data operating function	Comparison of 16-bit data	
Interrupt	The result of data comparison is not a match.	

Table 6.1 Operation Overview



Figure 6.1 Image of Operations



6.1.1 Project Settings

For the settings of the project to be used on the EWARM for development environment, refer to the Application Note: RZ/T1 Group Initial Settings.

6.2 Memory Map

For the address space of the RZ/T1 Group and a memory map of the RZ/T1 evaluation board, refer to the Application Note: RZ/T1 Group Initial Settings.

6.2.1 Assignment to Sections of Sample Program

Refer to the Application Note: RZ/T1 Group Initial Settings for the sections to be used in the program, assignment to sections (loading view) of the sample program in its initial state, and assignment to sections of the sample program following the application of scatter loading (execution view).

6.2.2 MPU Settings

For the settings of the MPU, refer to the Application Note: RZ/T1 Group Initial Settings.

6.2.3 Exception Processing Vector Table

For the vector table of exception processing, refer to the Application Note: RZ/T1 Group Initial Settings.

6.3 List of Interrupts

Table 6.2 shows interrupts to be used in the sample program.

Table 6.2 Interrupts for Sample Program

Interrupts (Source ID) Priority		Description	
ECM error detection interrupt (ERRD)	15	To check whether a data operation circuit error flag has been set, LED1 is turned on in case of an error.	
DMA transfer software startup interrupt (DMASRQ0)	15	When DMA transfer of all data of the on-chip extended RAM, LED0 is turned on and the failure detection test of the on-chip extended RAM is complete.	
DMA transfer error interrupt (DMAERR0)	15	To acknowledge that a data transfer error occurred.	



Fixed-Width Integer Types 6.4

Table 6.3 lists fixed-width integers to be used in the sample program.

Table 6.5	Fixed-width integers for Sample Program	
Symbol	Description	
int8_t	8-bit signed integer (defined in the standard library)	
int16_t	16-bit signed integer (defined in the standard library)	
int32_t	32-bit signed integer (defined in the standard library)	
int64_t	64-bit signed integer (defined in the standard library)	
uint8_t	8-bit unsigned integer (defined in the standard library)	
uint16_t	16-bit unsigned integer (defined in the standard library)	
uint32_t	32-bit unsigned integer (defined in the standard library)	
uint64_t	64-bit unsigned integer (defined in the standard library)	

Table 6.3 Fixed-Width Integers for Sample Program

6.5 **Constants/Error Codes**

 Table 6.4 lists constants of the sample program.

Table 6.4 **Constants for Sample Program**

Constant	Setting Value	Description
DOC_STAT_FLAG_SET	(1)	Indicates that the status flag is 1.
DOC_STAT_FLAG_CLEAR	(0)	Indicates that the status flag is 0.
DOC_CFG_PARAM_CHECKING_ENABLE	(1)	Indicates that parameter checking is enabled (1) or disabled (0) by using API function of the DOC.



6.6 Structures/Unions/Emulate Types

Figure 6.2 and Figure 6.3 show the structures, unions, and emulate types to be used in the sample program.

```
/* API ERROR RETURN CODES */
                           // DOC API error codes
typedef enum e_doc_err
{
   DOC_SUCCESS=0,
   DOC_ERR_OPEN_IGNORED,
                                   // The module has already been Open()ed
   DOC_ERR_INVALID_ARG,
                                 // Argument is not valid for parameter
   DOC_ERR_NULL_PTR,
                                 // Received null pointer or missing required argument
   DOC_ERR_NOT_OPENED
                                   // Open function has not yet been called
} doc_err_t;
/* Open() DEFINITIONS */
typedef enum e_doc_mode
                                   // DOC operation mode
   DOC_COMPARISON = 0x00u,
                                        // Data comparison mode
   DOC ADDITION = 0x01u,
                                       // Data addition mode
   DOC\_SUBSTRACTION = 0x02u,
                                        // Data substraction mode
   DOC PROHIBITED
} doc_mode_t;
typedef enum e_doc_detect
                                  // DOC detection condition
    DOC_MISMATCH = 0x00u,
                                        // Data mismatch is detected
   DOC_MATCH = 0x04u
                                        // Data match is detected
} doc_detect_t;
typedef enum e_doc_interrupt
                                 // DOC interrupt enable setting
    DOC_INTERRUPT_DISABLE = 0x00u, // Disables interrupt from DOC
   DOC_INTERRUPT_ENABLE = 0x10u
                                          // Enables interrupt from DOC
} doc_interrupt_t;
```

Figure 6.2 Structures/Unions/Enumerated Types for Sample Program



```
typedef struct st_doc_config
                                  /\!/ DOC configuration options used in Open function
                                        // DOC operation mode
    doc_mode_t
                     mode;
                                    // DOC detection condition
    doc_detect_t
                     detect;
    doc_interrupt_t
                    interrupt;
                                  // DOC interrupt enable setting
} doc_config_t;
/* Control() DEFINITIONS */
typedef enum e_doc_cmd
                                 // Command used in Control function
ł
    DOC_CMD_GET_STATUS,
                                        // Get DOC status flag
    DOC_CMD_CLEAR_STATUS
                                        // Clear DOC status flag
} doc_cmd_t;
```

Figure 6.3 Structures/Unions/Enumerated Types for Sample Program



6.7 Functions

 Table 6.5 lists the functions to be used.

Table 6.5 Functions

Function	Page Number	
main	14	
init_ram	14	
doc_init	15	
test_ram	15	
dmac0_init	15	
R_DOC_Open	16	
R_DOC_Control	16	
R_IRQ20_isr	17	
R_IRQ251_isr	17	
R_IRQ293_isr	17	

6.8 Specifications of Sample Program Functions

6.8.1 main

main

in	
Synopsis	Main processing
Declaration	int main (void)
Description	This function makes initial settings of the ports, ECM, ICU, DOC, DMAC, and on-chip extended RAM.
Arguments	None
Return value	None
Supplement	None

6.8.2 init_ram

init	ram

lam			
Synopsis	Initializing the on-chip extended RAM		
Declaration	void init_ram (uint32_t value)		
Description	This function initializes the 512-Kbyte area starting from 2200 0000H with the value of the value argument.		
Arguments	uint32_t value	Specifies the value to be initialized	
Return value	None		
Supplement	None		



6.8.3 doc_init

doc_init	doc_init		
Synopsis	Initializing data operation circuit		
Declaration	void doc_init (void)		
Description	This function makes initial settings of the data operation circuit.		
Arguments	None		
Return value	None		
Supplement	None		

6.8.4 test_ram

test_ram Synopsis Detecting failures of the on-chip extended RAM Declaration void test_ram (void) Description This function initializes the DMA controller (DMAC0) and performs DMA transfer of the data in the on-chip extended RAM to the DOC data input register in sequence. Arguments None Return value None Supplement None

6.8.5 dmac0_init

dmac0_init		
Synopsis	is Initializing DMA controller (DMAC0)	
Declaration	void dmac0_init (void)	
Description This function makes initial settings of the DMAC0.		
Arguments	None	
Return value	None	
Supplement	None	



6.8.6 R_DOC_Open

R_DOC_Open			
Synopsis	DOC open		
Header	r_doc_if.h		
Declaration	doc_err_t R_DOC_Open (void * const p_cfg)		
Description	This function initializes the DOC-related registers.		
Arguments	void * const p_cfg The pointer that stores data group to be set in the DOC control register Operating modes DOC_COMPARISON DOC_ADDITION DOC_SUBTRACTION Selection of conditions for detection DOC_MISMATCH DOC_MATCH DATA DOC_INTERRUPT_DISABLE DOC_INTERRUPT_ENABLE		
Return value	The result of execution of the open function DOC_SUCCESS: DOC initialized DOC_ERR_OPEN_IGNORED: DOC opened DOC_ERR_INVALID_ARG: Invalid values included in the element of the p_cfg structure DOC_ERR_NULL_PTR: p_cfg pointer null		
Supplement	Setting DOC_CFG_PARAM_CHECKING_ENABLE that is defined by r_doc_config.h to 1 enables checking of the parameters of the arguments.		

R_DOC_Control		
Synopsis	DOC control	
Header	r_doc_if.h	
Declaration	doc_err_t R_DOC_Control (doc_cmd_t const cmd, uint8_t * p_status)	
Description	This function reads and clears the state of the DOC.	
Arguments	doc_cmd_t const cmd	Specifies the command to be executed DOC_CMD_GET_STATUS DOC_CMD_CLEAR_STATUS
	uint8_t * p_status	The pointer to the position of storage of the status flags
Return value	 The result of the execution of the control function DOC_SUCCESS : Normal termination DOC_ERR_INVALID_ARG: Invalid argument value DOC_ERR_NULL_PTR : p_status null DOC_ERR_NOT_OPENED: Open unread 	
Supplement Setting DOC_CFG_PARAM_CHECKING_ENABLE that is defined by r_doc_conf checking of the parameters of the arguments.		

6.8.7 R_DOC_Control



6.8.8 R_IRQ20_isr

R_IRQ20_isr

Synopsis	IRQ20 interrupt (ECM error detection maskable interrupt)
Declaration	void R_IRQ20_isr (void)
Description	This function confirms the data operation circuit flag. LED1 is turned on when an error occurs. It clears the data operation circuit flag.
Arguments	None
Return value	None
Supplement	None

6.8.9 R_IRQ251_isr

D IDO251 ior			
	R_IRQ251_isr		
Synopsis	Synopsis IRQ251 interrupt (DMA transfer software startup interrupt)		
Declaration	void R_IRQ251_isr (void)		
Description	This function turns LED0 on when data transfer is complete.		
Arguments	None		
Return value	None		
Supplement	This interrupt source triggers the DMAC as a software startup source and is conveyed to the interrupt controller on completion of the DAM transfer as a DAM transfer completed interrupt.		

6.8.10 R_IRQ293_isr

R_IRQ293_isr		
Synopsis	IRQ293 interrupt (DMA transfer error interrupt)	
Declaration	void R_IRQ293_isr (void)	
Description This function recognizes bus errors.		
Arguments	uments None	
Return value	None	
Supplement	The program will not be in place if a bus error occurs. Add the program as required.	



6.9 Flowcharts

6.9.1 Main Processing

Figure 6.4 show a flow chart of main processing.



Figure 6.4 Main Processing



6.9.2 Initialization of On-Chip Extended RAM

Figure 6.5 show a flowchart of processing of initialization of the on-chip extended RAM.



Figure 6.5 Initialization of On-chip Extended RAM

6.9.3 Initialization of Data Operation Circuit

Figure 6.6 shows a flowchart of processing of initialization of the data operation circuit.







6.9.4 Detection of Failure of On-chip Extended RAM

Figure 6.7 shows a flowchart of detecting failures of the on-chip extended RAM.



Figure 6.7 Detecting Failures of On-Chip Extended RAM



6.9.5 Initialization of DMA Controller

Figure 6.8 shows a flowchart of processing of initialization of the DMA controller.







6.9.6 DOC Open Function

Figure 6.9 shows a flowchart of the DOC open function.







6.9.7 DOC Control Function

Figure 6.10 shows a flowchart of the DOC control function.



Figure 6.10 DOC Control Function

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6.9.8 IRQ20 Interrupt (ECM Error Detection Maskable Interrupt)

Figure 6.11 shows a flowchart of processing of the IRQ20 interrupt (ECM error detection maskable interrupt).



Figure 6.11 IRQ20 Interrupt (ECM Error Detection Maskable Interrupt)



6.9.9 IRQ251 Interrupt (DMA Transfer Software Startup Interrupt)

Figure 6.12 shows a flowchart of processing of the IRQ251 interrupt (DMA transfer software startup).



Figure 6.12 IRQ251 Interrupt (DMA Transfer Software Startup)

6.9.10 IRQ293 Interrupt (DMA Transfer Error Interrupt)

Figure 6.13 shows a flowchart of processing of the IRQ293 interrupt (DMA transfer error interrupt).



Figure 6.13 IRQ293 Interrupt (DMA Transfer Error Interrupt)



7. Sample Program

Download the sample program from the Renesas Electronics website.



8. Reference Documents

User's manual: hardware:

RZ/T1 Group User's Manual: Hardware

(Download the latest version of the manual from the Renesas Electronics website.)

RZ/T1 Evaluation Board RTK7910022C00000BR User's Manual (Download the latest version of the manual from the Renesas Electronics website.)

Technical Update / Technical News (Download the latest version of the update or news from the Renesas Electronics website.)

User's manual: Development Environment

For IAR integrated development environment (IAR Embedded Workbench[®] for Arm), visit the IAR Systems website. (Download the latest version from the IAR Systems website.)



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Revision I	History
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Application Note: Data Operation Circuit (DOC)

Rev.	Date	Description		
		Page	Summary	
0.10	Mar. 18, 2015	—	First Edition issued	
1.00	Apr. 10, 2015	—	Only the revision number was changed to be posted on a website.	
1.10 Aug. 18, 2015		2. Operating	Environment	
		5	Table 2.1 Operating Environment: Integrated Development Environment, partiallyamended and added	
		6. Software	·	
		10	6.2.4 Required Memory Size: Description and reference added	
		10	Table 6.2: Table title was partially amended	
		11	Table 6.3 added	
		11	Table 6.4 added	
1.20	Dec. 04, 2015	2. Operating	Environment	
		5	Table 2.1 Operating Environment: Integrated Development Environment, information partially amended	
1.30	Apr. 05, 2017	2. Operating	Environment	
		5	Table 2.1 Operating Environment: Integrated Development Environment, modified	
		6. Software	·	
		_	6.2.4 Required Memory Size, deleted	
1.40	Jun. 07, 2018	2. Operating	Environment	
		5	Table 2.1 Operating Environment: The description on the integrated development environ- ment, modified	
		5. Hardware	·	
		8	Figure 5.1 Hardware configuration example: The name of module, modified	
		8. Related Do	ocuments	
		27	The name of IAR Embedded Workbench, modified	

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